TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSIII)

2SK2604

Switching Regulator Applications

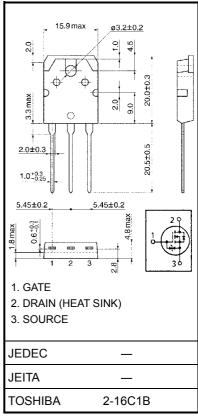
Unit: mm

• Low drain-source ON resistance $: RDS (ON) = 1.9 \Omega (typ.)$ • High forward transfer admittance $: |Y_{fs}| = 3.8 S (typ.)$ • Low leakage current $: IDSS = 100 \mu A (max) (VDS = 640 V)$

• Enhancement-mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	800	V	
Drain-gate voltage (Ro	_{SS} = 20k Ω)	V_{DGR}	800	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	5	Α	
	Pulse (Note 1)	I _{DP}	15	Α	
Drain power dissipation	n (Tc = 25°C)	P_{D}	125	W	
Single pulse avalanche	e energy (Note 2)	E _{AS}	370	mJ	
Avalanche current		I _{AR}	5	Α	
Repetitive avalanche e	nergy (Note 3)	E _{AR}	12.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	inge	T _{stg}	-55~150	°C	



Weight: 4.6 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.0	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 27 mH, R_G = 25 Ω , I_{AR} = 5 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

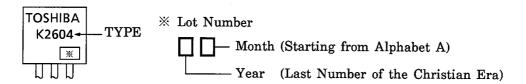
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 640 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	800	_	_	V
Gate threshold v	roltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3 A,	_	1.9	2.2	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 15 V, I _D = 3 A	1.0	3.8	_	S
Input capacitanc	е	C _{iss}			1080	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	16	_	
Output capacitance		Coss]		105	_	
Switching time	Rise time	t _r	$V_{GS} = \frac{10V}{0V}$ V_{OU} V_{OU} V_{OU} V_{OU} $V_{DD} = 200V$	_	40	_	- ns
	Turn-on time	t _{on}		_	80	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	_	140	_	
Total gate charge (gate-source plus gate-drain)		Qg			34	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		16	_	nC
Gate-drain ("miller") Charge		Q_{gd}			18	_	

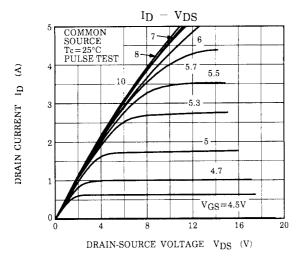
Source-Drain Ratings and Characteristics (Ta = 25°C)

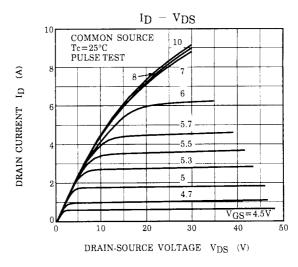
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}		_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}		_		15	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 5 A, V _{GS} = 0 V, dI _{DR} / dt = 100 A / μs	_	1000	_	ns
Reverse recovery charge	Q_{rr}	TDR - 5 Λ, VGS - 5 V, αιDR / αι - 100 Α / μs	_	7.5	_	μC

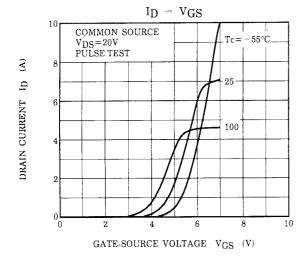
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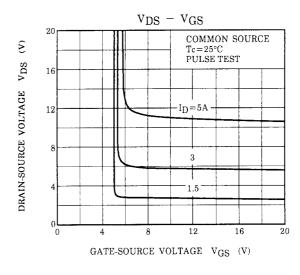


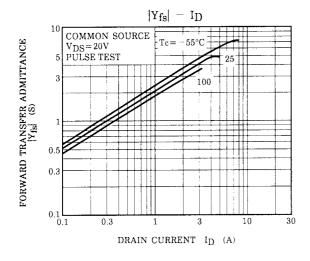
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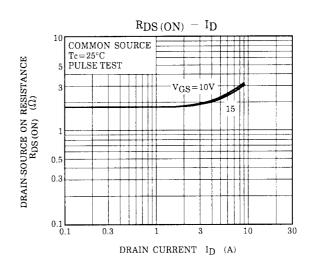




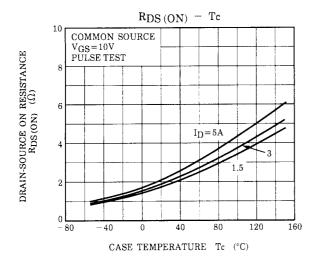


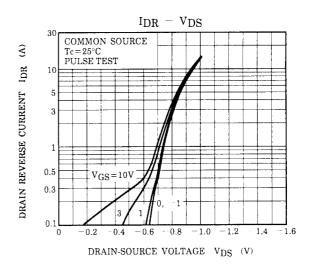


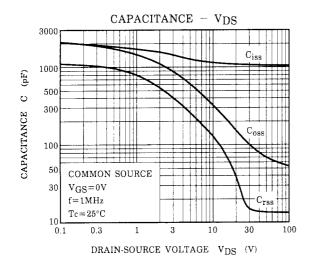


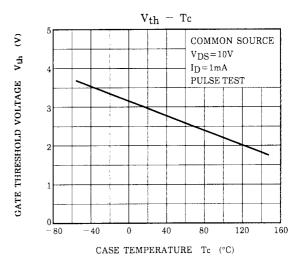


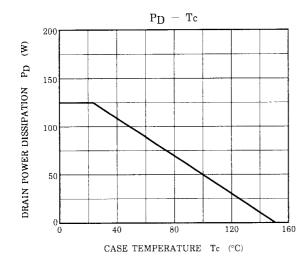
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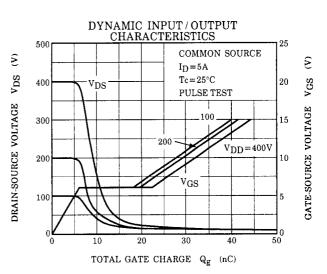




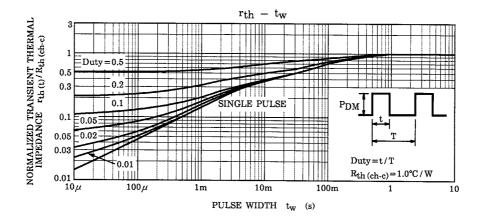


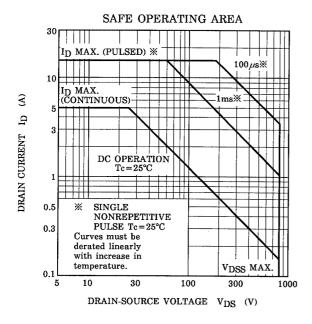


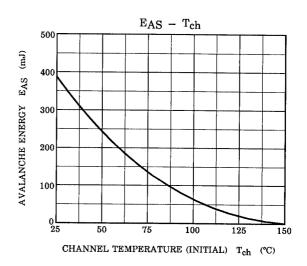


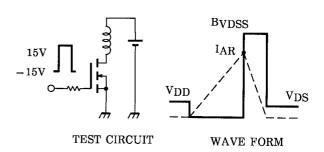


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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 27~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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